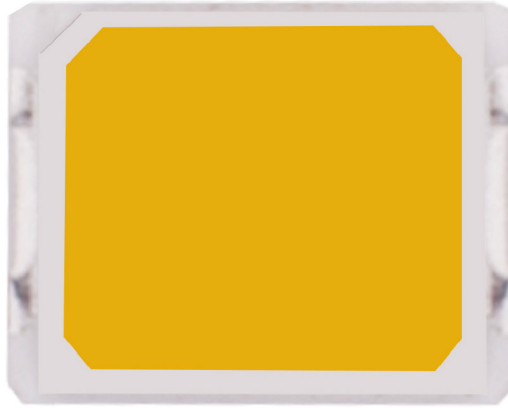




Bridgelux® SMD 2835 0.5W 3V

Product Data Sheet DS533

Introduction

SMD 2835



Features

- Industry-standard 2835 footprint
- Enables 3- and 6-step MacAdam ellipse custom binning kits
- RoHS compliant and lead free
- Multiple CCT configurations for a wide range of lighting applications

Benefits

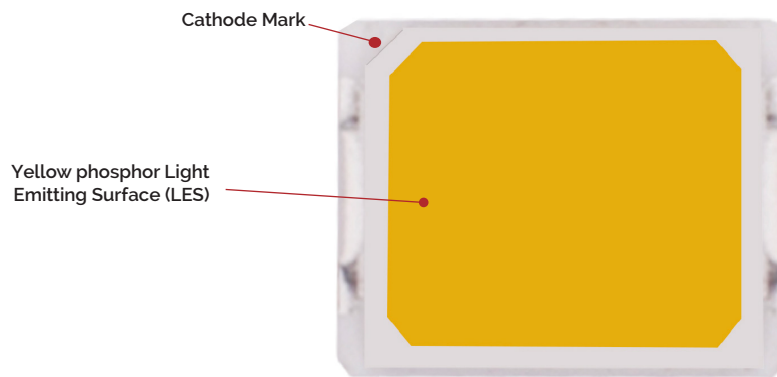
- Lower operating and manufacturing cost
- Ease of design and rapid go-to-market
- Uniform, consistent white light
- Reliable and constant white point
- Compliant with environmental standards
- Design flexibility

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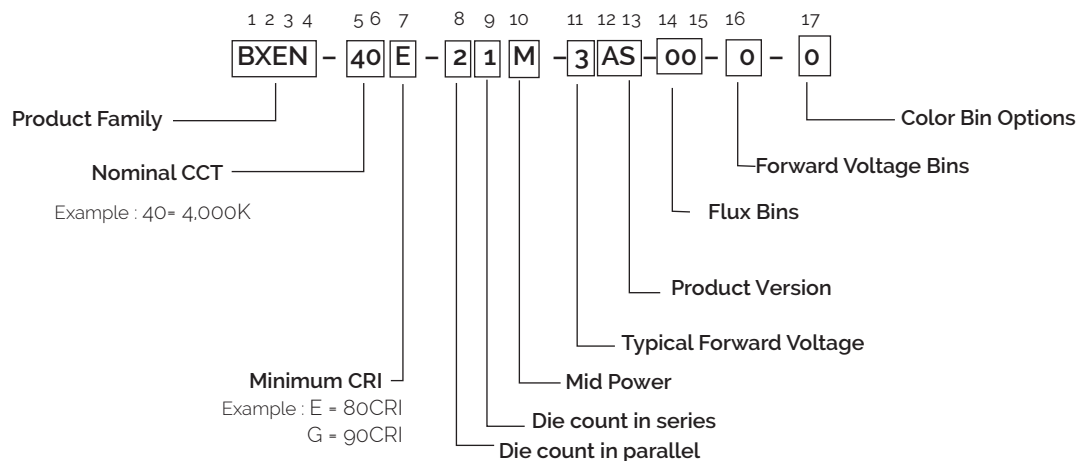
Product Feature Map

Bridgelux SMD LED products come in industry standard package sizes and follow ANSI binning standards. These LEDs are optimized for cost and performance, helping to ensure highly competitive system lumen per dollar performance while addressing the stringent efficacy and reliability standards required for modern lighting applications.



Product Nomenclature

The part number designation for Bridgelux SMD 2835 is explained as follows:



Product Selection Guide

The following product configurations are available:

Table 1: Selection Guide, Pulsed Measurement Data at 150mA ($T_j = T_{sp} = 25^\circ\text{C}$)

Part Number ^{1,6}	Nominal CCT ² (K)	CRI ^{3,5}	Nominal Drive Current (mA)	Forward Voltage ^{4,5} (V)			Typical Pulsed Flux (lm) ^{4,5}	Typical Power (W)	Typical Efficacy (lm/W)
				Min	Typical	Max			
BXEN-27E-21M-3AS-00-0-0	2700	80	150	2.70	2.95	3.20	69.5	0.4	157
BXEN-27G-21M-3AS-00-0-0	2700	89.5	150	2.70	2.95	3.20	59.1	0.4	133
BXEN-30E-21M-3AS-00-0-0	3000	80	150	2.70	2.95	3.20	71.5	0.4	162
BXEN-30G-21M-3AS-00-0-0	3000	89.5	150	2.70	2.95	3.20	60.8	0.4	138
BXEN-34E-21M-3AS-00-0-0	3400	80	150	2.70	2.95	3.20	71.5	0.4	162
BXEN-35E-21M-3AS-00-0-0	3500	80	150	2.70	2.95	3.20	71.5	0.4	162
BXEN-35G-21M-3AS-00-0-0	3500	89.5	150	2.70	2.95	3.20	60.8	0.4	138
BXEN-40E-21M-3AS-00-0-0	4000	80	150	2.70	2.95	3.20	75.5	0.4	171
BXEN-40G-21M-3AS-00-0-0	4000	89	150	2.70	2.95	3.20	64.2	0.4	145
BXEN-50E-21M-3AS-00-0-0	5000	80	150	2.70	2.95	3.20	75.5	0.4	171
BXEN-50G-21M-3AS-00-0-0	5000	89	150	2.70	2.95	3.20	64.2	0.4	145
BXEN-57E-21M-3AS-00-0-0	5700	80	150	2.70	2.95	3.20	75.5	0.4	171
BXEN-57G-21M-3AS-00-0-0	5700	89	150	2.70	2.95	3.20	64.2	0.4	145
BXEN-65E-21M-3AS-00-0-0	6500	80	150	2.70	2.95	3.20	75.0	0.4	169
BXEN-65G-21M-3AS-00-0-0	6500	89	150	2.70	2.95	3.20	64.2	0.4	145

Product Selection Guide

Table 2: Selection Guide, Pulsed Test Performance ($T_{sp} = 85^{\circ}\text{C}$)^{7,8}

Part Number ^{1,6}	Nominal CCT ² (K)	CRI ^{3,5}	Nominal Drive Current (mA)	Forward Voltage ^{4,5} (V)			Typical Pulsed Flux (lm) ^{4,5}	Typical Power (W)	Typical Efficacy (lm/W)
				Min	Typical	Max			
BXEN-27E-21M-3AS-00-0-0	2700	80	150	2.64	2.89	3.14	62.4	0.4	144
BXEN-27G-21M-3AS-00-0-0	2700	90	150	2.64	2.89	3.14	53.0	0.4	122
BXEN-30E-21M-3AS-00-0-0	3000	80	150	2.64	2.89	3.14	64.2	0.4	148
BXEN-30G-21M-3AS-00-0-0	3000	90	150	2.64	2.89	3.14	54.6	0.4	126
BXEN-34E-21M-3AS-00-0-0	3400	80	150	2.64	2.89	3.14	64.2	0.4	148
BXEN-35E-21M-3AS-00-0-0	3500	80	150	2.64	2.89	3.14	64.2	0.4	148
BXEN-35G-21M-3AS-00-0-0	3500	90	150	2.64	2.89	3.14	54.6	0.4	126
BXEN-40E-21M-3AS-00-0-0	4000	80	150	2.64	2.89	3.14	67.8	0.4	156
BXEN-40G-21M-3AS-00-0-0	4000	90	150	2.64	2.89	3.14	57.6	0.4	133
BXEN-50E-21M-3AS-00-0-0	5000	80	150	2.64	2.89	3.14	67.8	0.4	156
BXEN-50G-21M-3AS-00-0-0	5000	90	150	2.64	2.89	3.14	57.6	0.4	133
BXEN-57E-21M-3AS-00-0-0	5700	80	150	2.64	2.89	3.14	67.8	0.4	156
BXEN-57G-21M-3AS-00-0-0	5700	90	150	2.64	2.89	3.14	57.6	0.4	133
BXEN-65E-21M-3AS-00-0-0	6500	80	150	2.64	2.89	3.14	67.3	0.4	155
BXEN-65G-21M-3AS-00-0-0	6500	90	150	2.64	2.89	3.14	57.6	0.4	133

Notes for Tables 1 & 2:

- The last 6 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-0-0" denotes the full distribution of flux, forward voltage, and color bin.
Example: BXEN-40E-21M-3AS-00-0-0 refers to the full distribution of flux, forward voltage, and color within a 4000K 6-step ANSI standard chromaticity region with a minimum of 80 CRI, 2x1 die configuration, medium power, 2.95V typical forward voltage.
- 80 CRI product CCT is cold targeted at $T_{sp} = 25^{\circ}\text{C}$ and 90 CRI product CCT is hot targeted at $T_{sp} = 85^{\circ}\text{C}$. Nominal CCT as defined by ANSI C78.377-2011.
- Listed CRIs are minimum values.
- Products tested under pulsed condition (10ms pulse width) at nominal drive current where $T_j = T_{sp} = 25^{\circ}\text{C}$.
- Bridgelux maintains a $\pm 7.5\%$ tolerance on luminous flux measurements, $\pm 0.1\text{V}$ tolerance on forward voltage measurements, and ± 2 tolerance on CRI measurements for the SMD 2835.
- Refer to Table 6 and Table 7 for Bridgelux SMD 2835 Luminous Flux Binning and Forward Voltage Binning information.
- Typical pulsed test performance values are provided as reference only and are not a guarantee of performance.
- Typical performance is estimated based on operation under pulsed current with LED emitter mounted onto a heat sink with thermal interface material and the solder point temperature maintained at 85°C . Based on Bridgelux test setup, values may vary depending on the thermal design of the luminaire and the exposed environment to which the product is subjected.

Performance at Commonly Used Drive Currents

SMD 2835 LEDs are tested to the specifications shown using the nominal drive currents in Table 1. SMD 2835 may also be driven at other drive currents dependent on specific application design requirements. The performance at any drive current can be derived from the current vs. voltage characteristics shown in Figure 2 and the relative luminous flux vs. current characteristics shown in Figure 3. The performance at commonly used drive currents is summarized in Table 3.

Table 3: Performance at Commonly Used Drive Currents

Part Number	CRI	Drive Current ¹ (mA)	Typical V_f $T_{sp} = 25^\circ\text{C}$ (V)	Typical Power $T_{sp} = 25^\circ\text{C}$ (W)	Typical Pulsed Flux ² $T_{sp} = 25^\circ\text{C}$ (lm)	Typical Pulsed Flux ² $T_{sp} = 85^\circ\text{C}$ (lm)	Typical Efficacy $T_{sp} = 25^\circ\text{C}$ (lm/W)
BXEN-27E-21M-3AS-00-0-0	80	30	2.65	0.1	15.1	13.2	190
		42	2.69	0.1	21.0	16.8	185
		65	2.73	0.2	32.0	26.9	180
		90	2.81	0.3	43.4	36.0	171
		120	2.88	0.3	56.5	46.8	163
		150	2.95	0.4	69.5	62.4	157
BXEN-27G-21M-3AS-00-0-0	89.5	30	2.65	0.1	12.8	11.2	162
		42	2.69	0.1	17.9	14.3	157
		65	2.73	0.2	27.2	22.9	153
		90	2.81	0.3	36.9	30.6	145
		120	2.88	0.3	48.0	39.8	139
		150	2.95	0.4	59.1	53.0	133
BXEN-30E-21M-3AS-00-0-0	80	30	2.65	0.1	15.5	13.5	196
		42	2.69	0.1	21.6	17.2	191
		65	2.73	0.2	32.9	27.5	185
		90	2.81	0.3	44.6	36.8	176
		120	2.88	0.3	58.2	47.8	168
		150	2.95	0.4	71.5	63.8	162
BXEN-34E-21M-3AS-00-0-0	80	30	2.65	0.1	15.5	13.5	196
		42	2.69	0.1	21.6	17.2	191
		65	2.73	0.2	32.9	27.5	185
		90	2.81	0.3	44.6	36.8	176
		120	2.88	0.3	58.2	47.8	168
		150	2.95	0.4	71.5	63.8	162
BXEN-30G-21M-3AS-00-0-0	89.5	30	2.65	0.1	13.2	11.5	167
		42	2.69	0.1	18.4	14.6	162
		65	2.73	0.2	28.0	23.4	157
		90	2.81	0.3	37.9	31.3	150
		120	2.88	0.3	49.5	40.6	143
		150	2.95	0.4	60.8	54.2	138
BXEN-35E-21M-3AS-00-0-0	80	30	2.65	0.1	15.5	13.5	196
		42	2.69	0.1	21.6	17.2	191
		65	2.73	0.2	32.9	27.5	185
		90	2.81	0.3	44.6	36.8	176
		120	2.88	0.3	58.2	47.8	168
		150	2.95	0.4	71.5	63.8	162
BXEN-35G-21M-3AS-00-0-0	89.5	30	2.65	0.1	13.2	11.5	167
		42	2.69	0.1	18.4	14.6	162
		65	2.73	0.2	28.0	23.4	157
		90	2.81	0.3	37.9	31.3	150
		120	2.88	0.3	49.5	40.6	143
		150	2.95	0.4	60.8	54.2	138

Performance at Commonly Used Drive Currents

Table 3: Performance at Commonly Used Drive Currents

Part Number	CRI	Drive Current ¹ (mA)	Typical V_f $T_{sp} = 25^\circ\text{C}$ (V)	Typical Power $T_{sp} = 25^\circ\text{C}$ (W)	Typical Pulsed Flux ² $T_{sp} = 25^\circ\text{C}$ (lm)	Typical Pulsed Flux ² $T_{sp} = 85^\circ\text{C}$ (lm)	Typical Efficacy $T_{sp} = 25^\circ\text{C}$ (lm/W)
BXEN-40E-21M-3AS-00-0-0	80	30	2.65	0.1	16.4	14.3	207
		42	2.69	0.1	22.8	18.2	201
		65	2.73	0.2	34.5	29.2	194
		90	2.81	0.3	47.1	39.1	186
		120	2.88	0.3	61.4	50.8	178
		150	2.95	0.4	75.5	67.8	171
BXEN-40G-21M-3AS-00-0-0	89	30	2.65	0.1	13.9	12.2	176
		42	2.69	0.1	19.4	15.5	171
		65	2.73	0.2	29.3	24.8	165
		90	2.81	0.3	40.0	33.2	158
		120	2.88	0.3	52.2	43.2	151
		150	2.95	0.4	64.2	57.6	145
BXEN-50E-21M-3AS-00-0-0	80	30	2.65	0.1	16.4	14.3	207
		42	2.69	0.1	22.8	18.2	201
		65	2.73	0.2	34.5	29.2	194
		90	2.81	0.3	47.1	39.1	186
		120	2.88	0.3	61.4	50.8	178
		150	2.95	0.4	75.5	67.8	171
BXEN-50G-21M-3AS-00-0-0	89	30	2.65	0.1	13.9	12.2	176
		42	2.69	0.1	19.4	15.5	171
		65	2.73	0.2	29.3	24.8	165
		90	2.81	0.3	40.0	33.2	158
		120	2.88	0.3	52.2	43.2	151
		150	2.95	0.4	64.2	57.6	145
BXEN-57E-21M-3AS-00-0-0	80	30	2.65	0.1	16.4	14.3	207
		42	2.69	0.1	22.8	18.2	201
		65	2.73	0.2	34.5	29.2	194
		90	2.81	0.3	47.1	39.1	186
		120	2.88	0.3	61.4	50.8	178
		150	2.95	0.4	75.5	67.8	171
BXEN-57G-21M-3AS-00-0-0	89	30	2.65	0.1	13.9	12.2	176
		42	2.69	0.1	19.4	15.5	171
		65	2.73	0.2	29.3	24.8	165
		90	2.81	0.3	40.0	33.2	158
		120	2.88	0.3	52.2	43.2	151
		150	2.95	0.4	64.2	57.6	145
BXEN-65E-21M-3AS-00-0-0	80	30	2.65	0.1	16.3	14.2	205
		42	2.69	0.1	22.6	18.1	200
		65	2.73	0.2	34.3	29.0	193
		90	2.81	0.3	46.8	38.8	185
		120	2.88	0.3	61.0	50.5	176
		150	2.95	0.4	75.0	67.3	169
BXEN-65G-21M-3AS-00-0-0	89	30	2.65	0.1	13.9	12.2	176
		42	2.69	0.1	19.4	15.5	171
		65	2.73	0.2	29.3	24.8	165
		90	2.81	0.3	40.0	33.2	158
		120	2.88	0.3	52.2	43.2	151
		150	2.95	0.4	64.2	57.6	145

Notes for Table 3:

1. Alternate drive currents in Table 3 are provided for reference only and are not a guarantee of performance.
2. Bridgelux maintains a $\pm 7.5\%$ tolerance on flux measurements.
3. Typical stabilized pulsed performance values are provided as reference only and are not a guarantee of performance.

Electrical Characteristics

Table 4: Electrical Characteristics

Part Number	Drive Current (mA)	Forward Voltage (V) ^{1,2}			Typical Temperature Coefficient of Forward Voltage $\Delta V_f / \Delta T$ (mV/°C)	Typical Thermal Resistance Junction to Solder Point ³ R_{j-sp} (°C/W)
		Minimum	Typical	Maximum		
BXEN-xxx-21M-3AS-00-0-0	150	2.70	2.95	3.20	-1.01	19

Notes for Table 4:

1. Bridgelux maintains a tolerance of $\pm 0.1V$ on forward voltage measurements. Voltage minimum and maximum values at the nominal drive current are guaranteed by 100% test.
2. Products tested under pulsed condition (10ms pulse width) at nominal drive current where $T_{sp} = 25^{\circ}C$.
3. Thermal resistance value was calculated using total electrical input power; optical power was not subtracted from input power.

Absolute Maximum Ratings

Table 5: Maximum Ratings

Parameter	Maximum Rating
LED Junction Temperature (T_j)	125°C
Storage Temperature	-40°C to +105°C
Operating Solder Point Temperature (T_{sp})	-40°C to +105°C
Soldering Temperature	260°C or lower for a maximum of 10 seconds
Maximum Drive Current	350mA
Maximum Peak Pulsed Forward Current ¹	400mA
Maximum Reverse Voltage ²	-
Moisture Sensitivity Rating	MSL 3
Electrostatic Discharge	2kV HBM. JEDEC-JS-001-HBM and JEDEC-JS-001-2012

Notes for Table 5:

1. Bridgelux recommends a maximum duty cycle of 10% and pulse width of 10 ms when operating LED SMD at maximum peak pulsed current specified. Maximum peak pulsed current indicate values where LED SMD can be driven without catastrophic failures.
2. Light emitting diodes are not designed to be driven in reverse voltage and will not produce light under this condition. no rating is provided

Product Bin Definitions

Table 6 lists the standard photometric luminous flux bins for Bridgelux SMD 2835 LEDs. Although several bins are listed, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all CCTs.

Table 6: Luminous flux Bin Definitions at 150mA, $T_{sp}=25^{\circ}\text{C}$

Bin Code	Minimum	Maximum	Unit	Condition
2B	55	60	lm	$I_F=150\text{mA}$
2C	60	65		
2D	65	70		
2E	70	75		
2F	75	80		

Note for Table 6:

1. Bridgelux maintains a tolerance of $\pm 7.5\%$ on luminous flux measurements.

Table 7: Forward Voltage Bin Definition at 150mA, $T_{sp}=25^{\circ}\text{C}$

Bin Code	Minimum	Maximum	Unit	Condition
9	2.7	2.8	V	$I_F=150\text{mA}$
A	2.8	2.9		
B	2.9	3.0		
C	3.0	3.1		
D	3.1	3.2		

Note for Table 7:

1. Bridgelux maintains a tolerance of $\pm 0.1\text{V}$ on forward voltage measurements.

Product Bin Definitions

Table 8: MacAdam Ellipse Color Bin Definitions

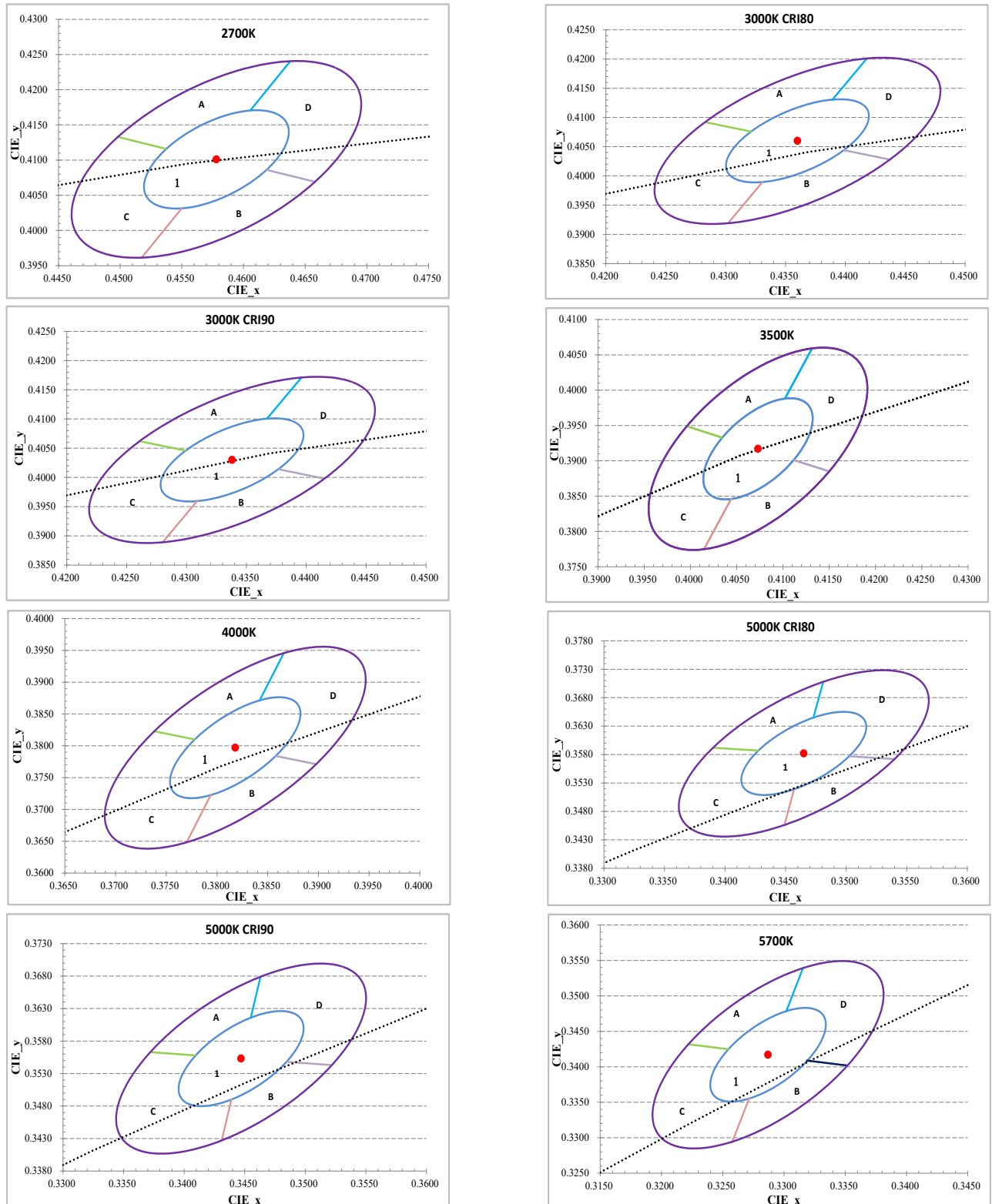
CCT	Color Space	Center Point		Major Axis	Minor Axis	Ellipse Rotation Angle	Color Bin
		X	Y				
2700K	3 SDCM	0.4578	0.4101	0.0081	0.0042	53.70	1
	6 SDCM	0.4578	0.4101	0.0162	0.0084	53.70	1/A/B/C/D
3000K CRI80	3 SDCM	0.4360	0.4060	0.00834	0.00408	53.22	1
	6 SDCM	0.4360	0.4060	0.01668	0.00816	53.22	1/A/B/C/D
3000K CRI90	3 SDCM	0.4338	0.4030	0.00834	0.00408	53.22	1
	6 SDCM	0.4338	0.4030	0.01668	0.00816	53.22	1/A/B/C/D
3400K	3 SDCM	0.4105	0.3938	0.00834	0.00408	54.00	1
	6 SDCM	0.4105	0.3938	0.01668	0.00816	54.00	1/A/B/C/D
3500K	3 SDCM	0.4073	0.3917	0.00927	0.00414	54.00	1
	6 SDCM	0.4073	0.3917	0.01854	0.00828	54.00	1/A/B/C/D
4000K	3 SDCM	0.3818	0.3797	0.00939	0.00402	53.72	1
	6 SDCM	0.3818	0.3797	0.01878	0.00804	53.72	1/A/B/C/D
5000K CRI80	3 SDCM	0.3465	0.3582	0.00822	0.00354	59.62	1
	6 SDCM	0.3465	0.3582	0.01644	0.00708	59.62	1/A/B/C/D
5000K CRI90	3 SDCM	0.3447	0.3553	0.00822	0.00354	59.62	1
	6 SDCM	0.3447	0.3553	0.01644	0.00708	59.62	1/A/B/C/D
5700K	3 SDCM	0.3287	0.3417	0.00746	0.00320	59.09	1
	6 SDCM	0.3287	0.3417	0.01492	0.00640	59.09	1/A/B/C/D
6500K	3 SDCM	0.3123	0.3282	0.00669	0.00285	58.57	1
	6 SDCM	0.3123	0.3282	0.01338	0.0057	58.57	1/A/B/C/D

Notes for Table 8:

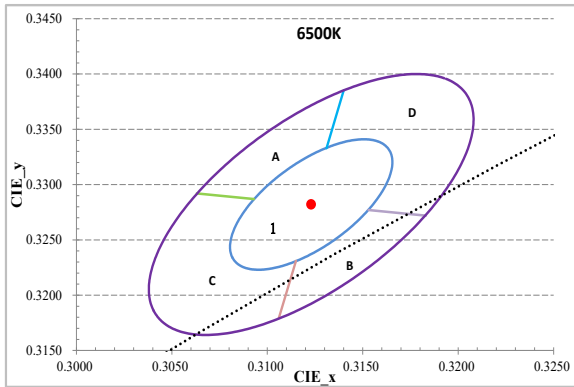
- 80 CRI product Color binning at $T_{sp}=25^{\circ}\text{C}$ and 90 CRI product Color binning at $T_{sp}=85^{\circ}\text{C}$ unless otherwise specified.
- Bridgelux maintains a tolerance of ± 0.007 on x and y color coordinates in the CIE 1931 color space.

Product Bin Definitions

Figure 1: C.I.E. 1931 Chromaticity Diagram (5 Color Bin Structure, 80 CRI Cold-color Targeted at $T_{sp}=25^{\circ}\text{C}$ and 90 CRI Hot-color Targeted at $T_{sp}=85^{\circ}\text{C}$)



Product Bin Definitions



Performance Curves

Figure 2: Drive Current vs. Forward Voltage ($T_{sp}=25^{\circ}\text{C}$)

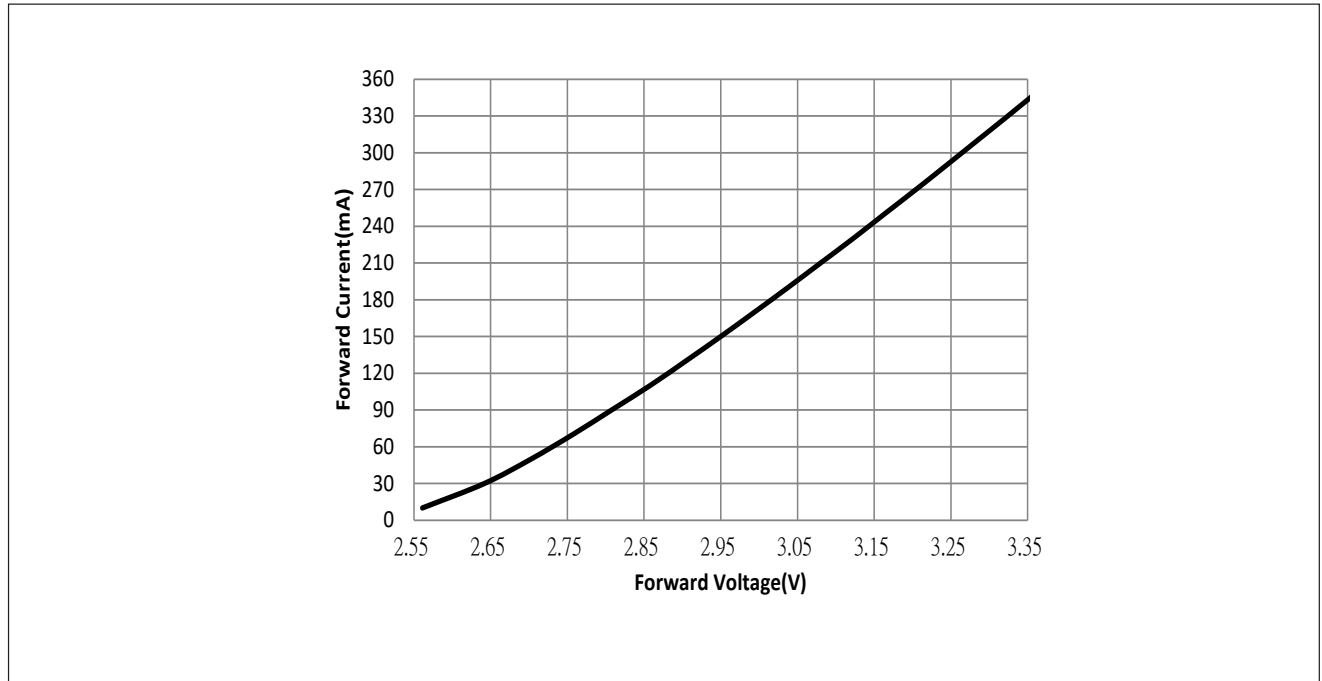
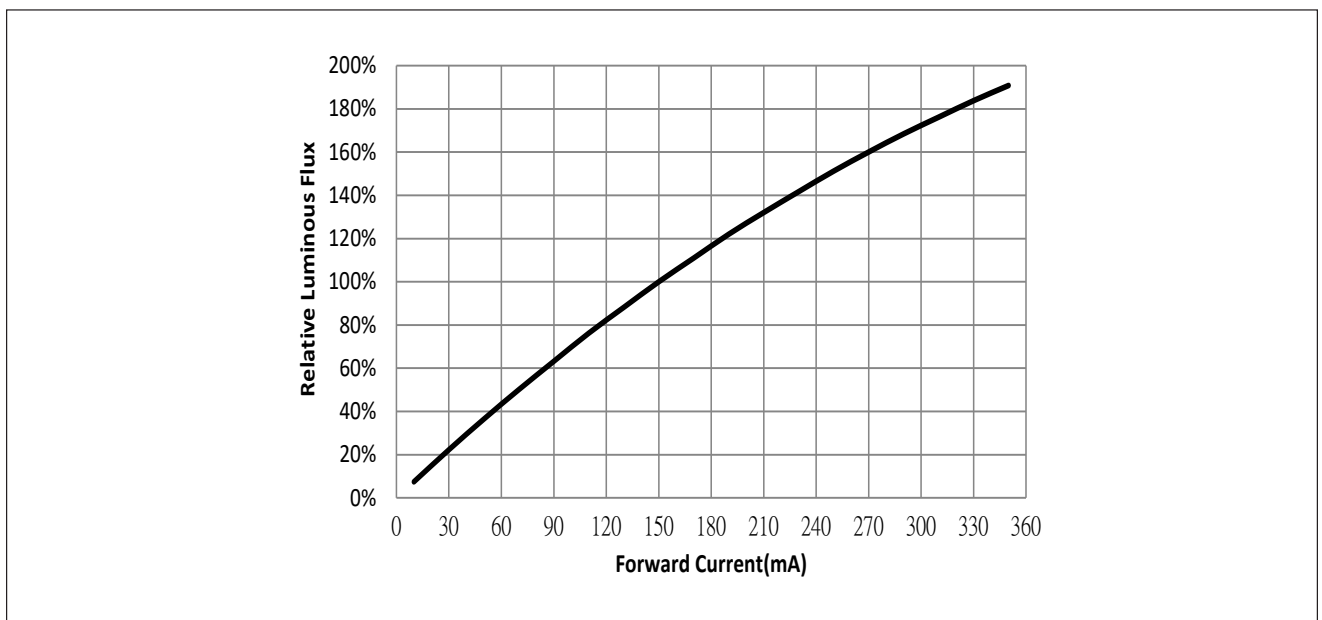


Figure 3: Relative Luminous Flux vs. Forward Current ($T_{sp}=25^{\circ}\text{C}$)



Note for Figure 3:

1. Pulse width modulation (PWM) is recommended for dimming effects.

Performance Curves

Figure 4: Relative Flux vs. Solder Point Temperature

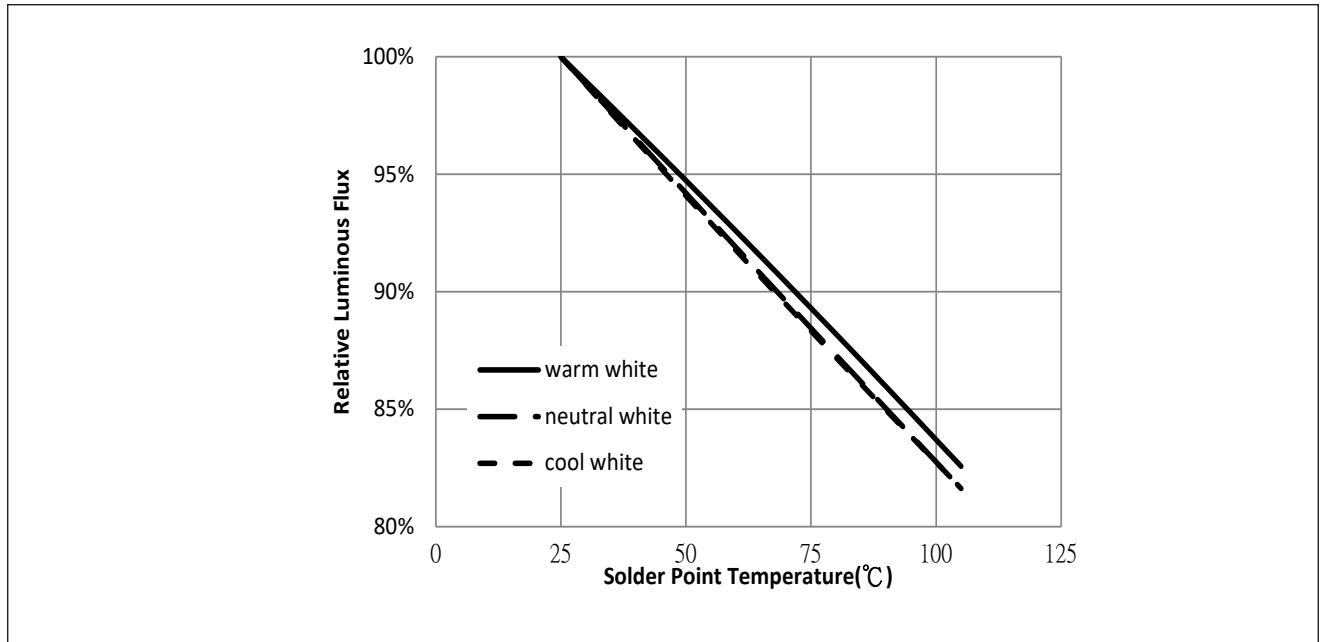
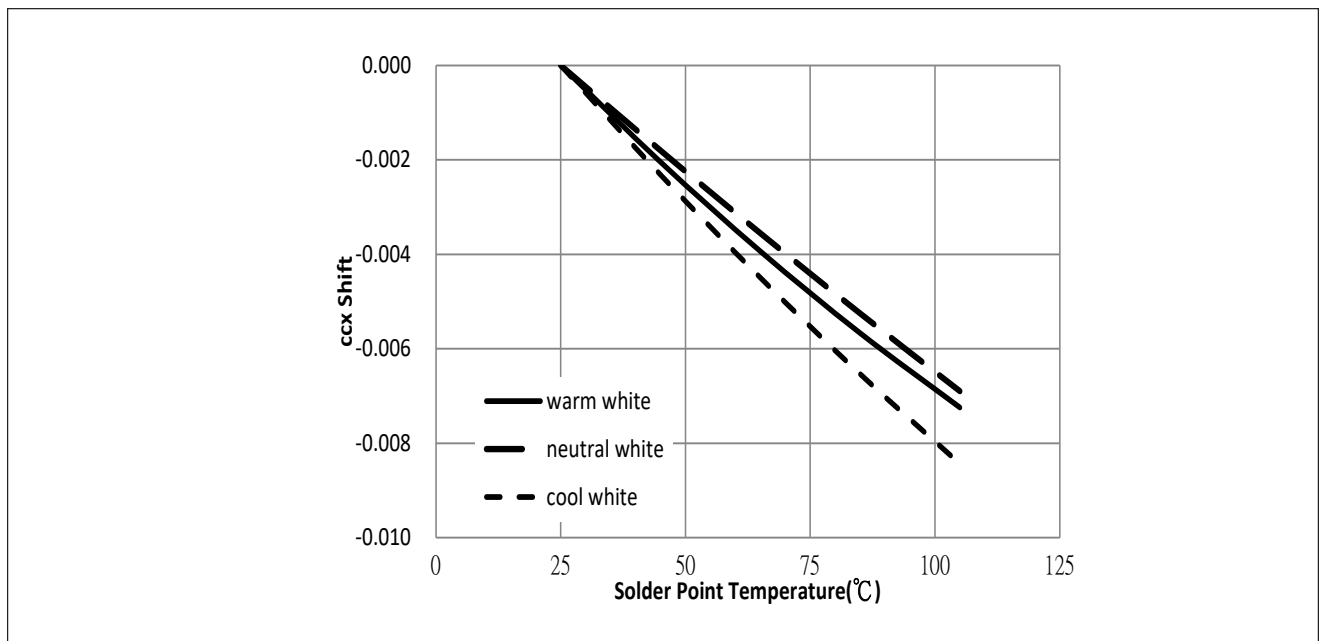


Figure 5: Typical ccx Shift vs. Solder Point Temperature

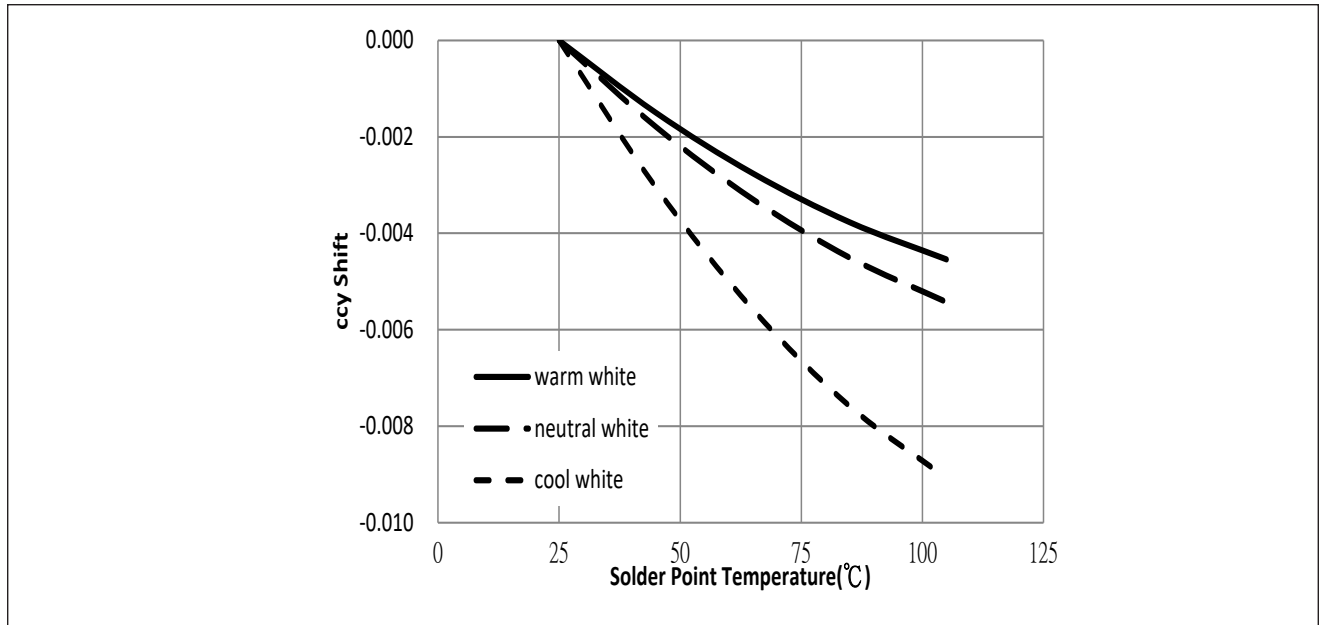


Notes for Figures 4 & 5:

1. Characteristics shown for warm white based on 3000K and 80 CRI.
2. Characteristics shown for neutral white based on 4000K and 80 CRI.
3. Characteristics shown for cool white based on 6500K and 80 CRI.
4. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

Performance Curves

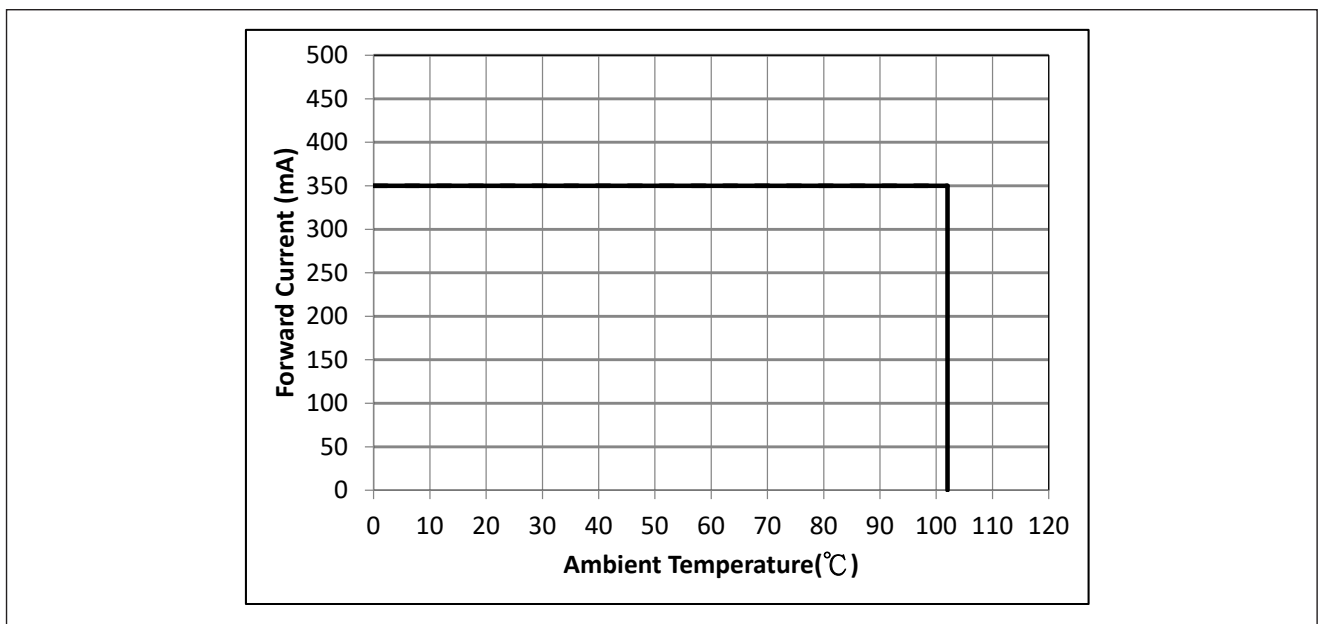
Figure 6: Typical ccy Shift vs. Solder Point Temperature



Notes for Figure 6:

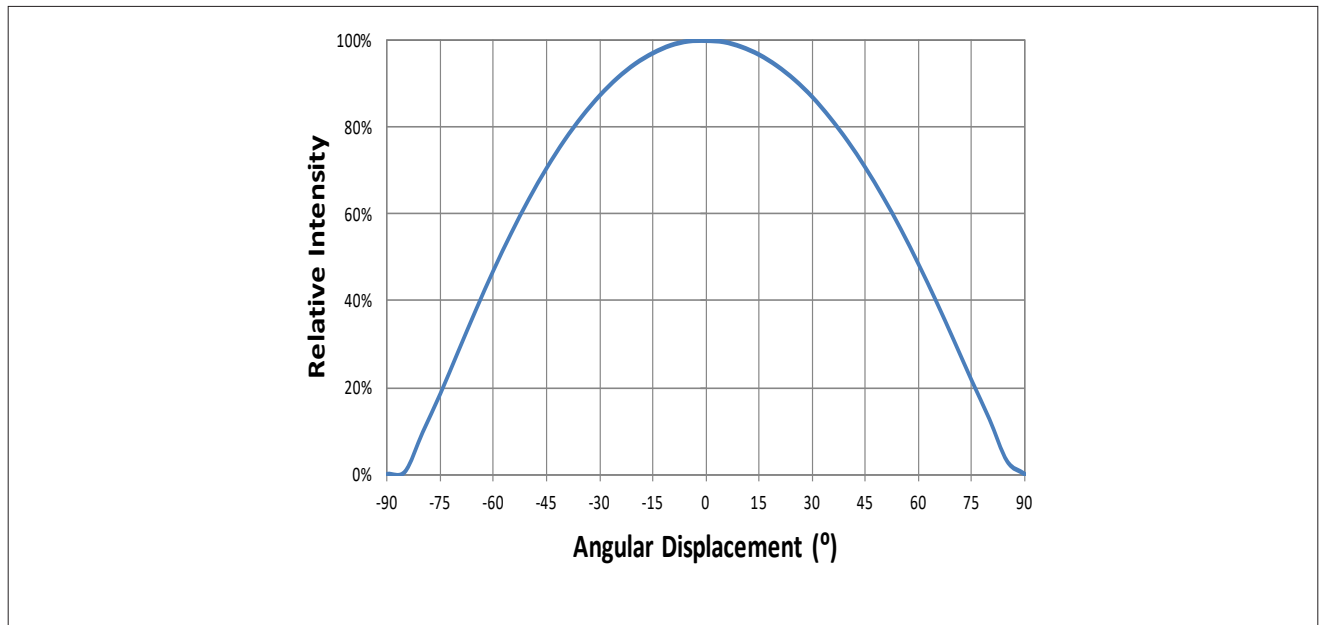
1. Characteristics shown for warm white based on 3000K and 80 CRI.
2. Characteristics shown for neutral white based on 4000K and 80 CRI.
3. Characteristics shown for cool white based on 6500K and 80 CRI.
4. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

Figure 7: Forward Current vs. Ambient Temperature



Typical Radiation Pattern

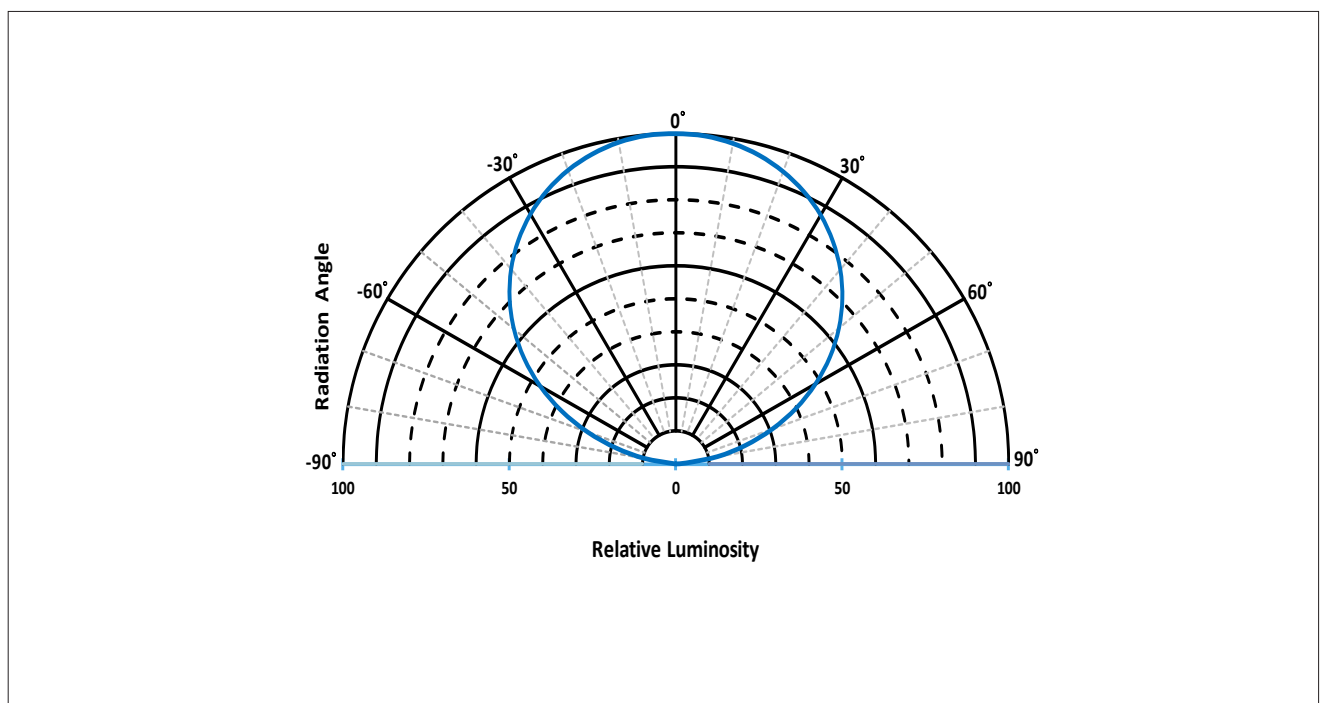
Figure 8: Typical Spatial Radiation Pattern at 150mA, $T_{sp}=25^{\circ}\text{C}$



Notes for Figure 8:

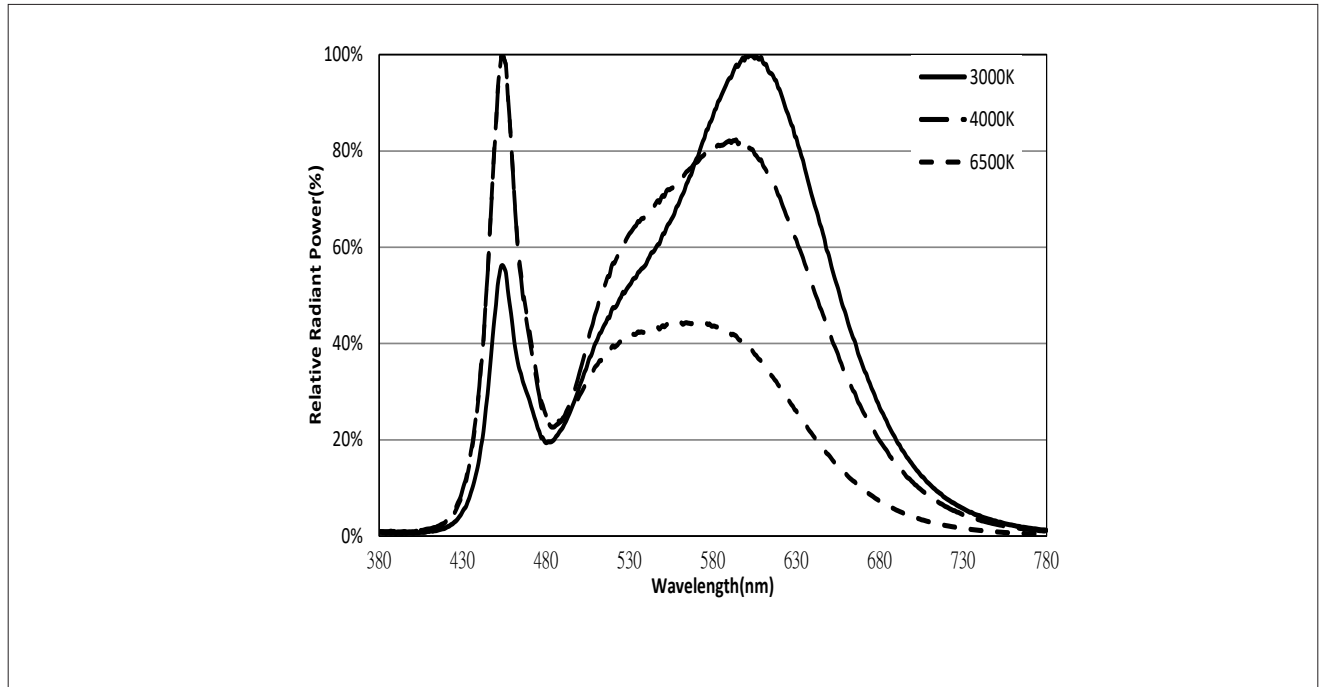
1. Typical viewing angle is 120° .
2. The viewing angle is defined as the off axis angle from the centerline where luminous intensity (Iv) is $\frac{1}{2}$ of the peak value.

Figure 9: Typical Polar Radiation Pattern at 150mA, $T_{sp}=25^{\circ}\text{C}$



Typical Color Spectrum

Figure 10: Typical Color Spectrum

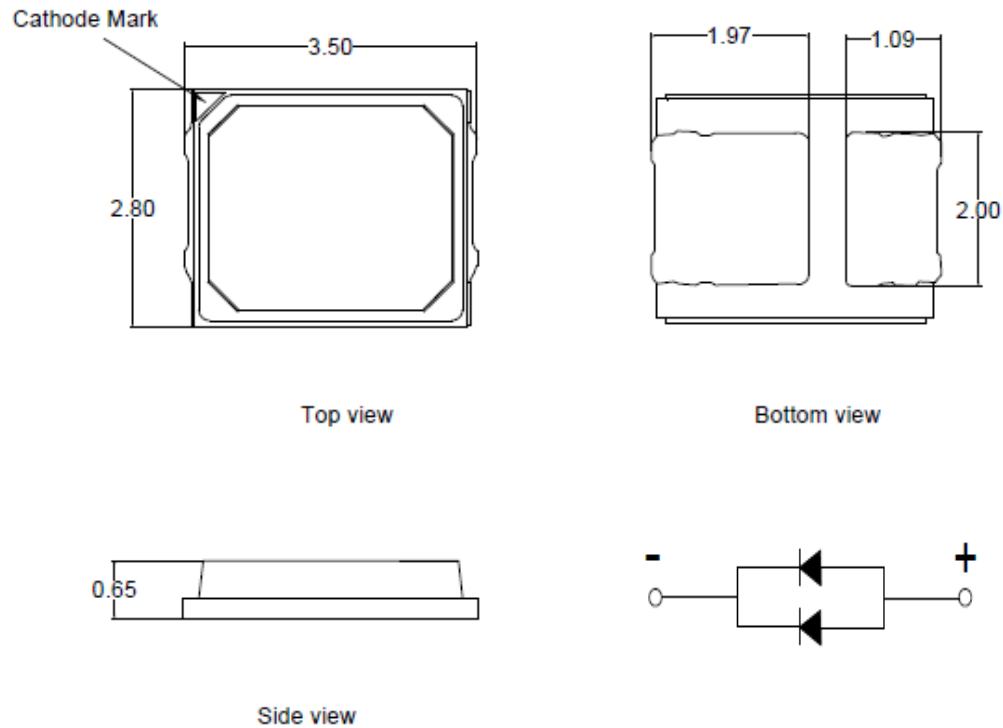


Notes for Figure 10:

1. Color spectra measured at nominal current for $T_{sp} = 25^{\circ}\text{C}$
2. Color spectra shown for 80 CRI products.

Mechanical Dimensions

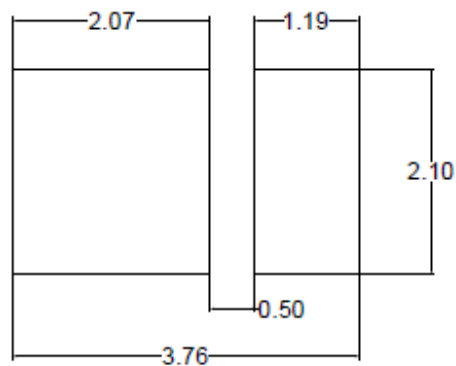
Figure 11: Drawing for SMD 2835



Notes for Figure 11:

1. Drawings are not to scale.
2. Drawing dimensions are in millimeters.
3. Unless otherwise specified, tolerances are $\pm 0.10\text{mm}$.

Recommended PCB Soldering Pad Pattern



Reliability

Table 8: Reliability Test Items and Conditions

No.	Items	Reference Standard	Test Conditions	Drive Current	Test Duration	Units Failed/Tested
1	Moisture/Reflow Sensitivity	J-STD-020E	$T_{\text{slid}} = 260^{\circ}\text{C}$, 10sec, Precondition: 30°C , 60%RH, 168hr	-	3 reflows	0/20
2	Low Temperature Storage	JESD22-A119	$T_a = -40^{\circ}\text{C}$	-	1000 hours	0/20
3	High Temperature Storage	JESD22-A103D	$T_a = 100^{\circ}\text{C}$	-	1000 hours	0/20
4	Low Temperature Operating Life	JESD22-A108D	$T_a = -40^{\circ}\text{C}$	150mA	1000 hours	0/20
5	Temperature Humidity Operating Life	JESD22-A101C	$T_{\text{sp}} = 85^{\circ}\text{C}$, RH=85%	150mA	1000 hours	0/20
6	High Temperature Operating Life	JESD22-A108D	$T_{\text{sp}} = 105^{\circ}\text{C}$	350mA	1000 hours	0/20
7	Thermal Shock	JESD22-A106B	$T_a = -40^{\circ}\text{C} \sim 100^{\circ}\text{C}$; Dwell: 15min; Transfer: 10sec	-	200 cycles	0/20
8	Temperature Cycle	JESD22-A104E	$T_a = -40^{\circ}\text{C} \sim 100^{\circ}\text{C}$; Dwell at extreme temperature: 15min; Ramp rate $< 10^{\circ}\text{C}/\text{min}$	-	200 cycles	0/20
9	Electrostatic Discharge	JS-001-2012	HBM, 2kV, 15k Ω , 100pF, Alternately positive or negative	-	-	0/20

Passing Criteria

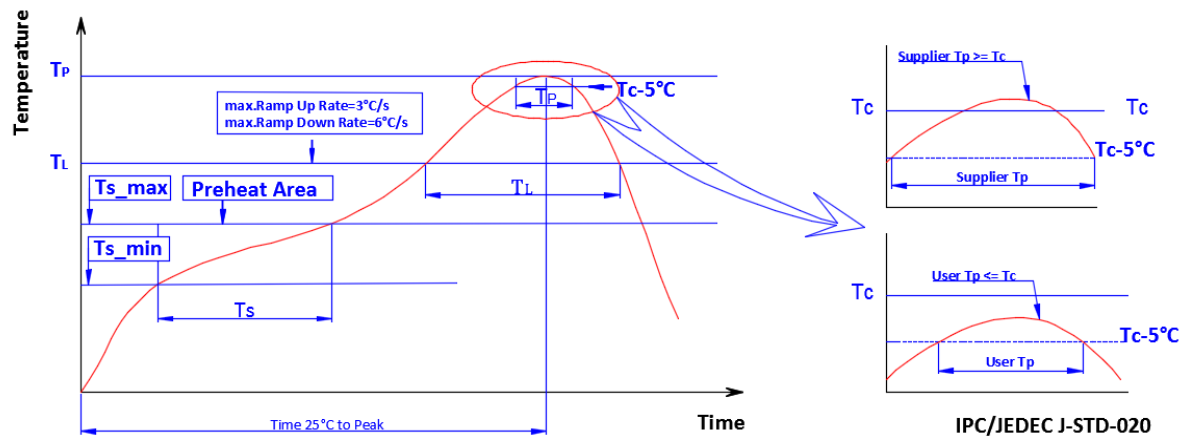
Item	Symbol	Test Condition	Passing Criteria
Forward Voltage	Vf	150mA	$\Delta V_f < 10\%$
Luminous Flux	Fv	150mA	$\Delta F_v < 30\%$
Chromaticity Coordinates	(x, y)	150mA	$\Delta u'v' < 0.007$

Notes for Table 8:

- Measurements are performed after allowing the LEDs to return to room temperature
- T_{slid} : reflow soldering temperature; T_a : ambient temperature

Reflow Characteristics

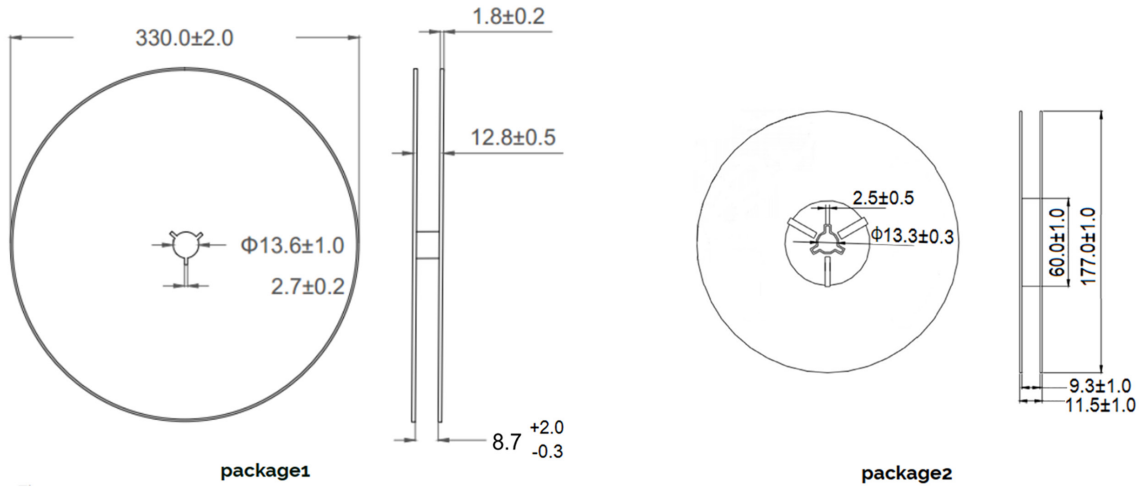
Figure 12 : Reflow Profile



Profile Feature	Lead Free Assembly
Temperature Min. (Ts_min)	160°C
Temperature Max. (Ts_max)	205°C
Time (ts) from Ts_min to Ts_max	60-150 seconds
Ramp-Up Rate (TL to Tp)	3 °C/second
Liquidus Temperature (TL)	220 °C
Time (TL) Maintained Above TL	60-150 seconds
Peak Temp(Tp)	260 °C max.
Time (Tp) Within 5 °C of the Specified Classification Temperature (Tc)	25 seconds max.
Ramp-Down Rate (Tp to TL)	5 °C/second max.
Time 25 °C to Peak Temperature	10 minutes max.

Packaging

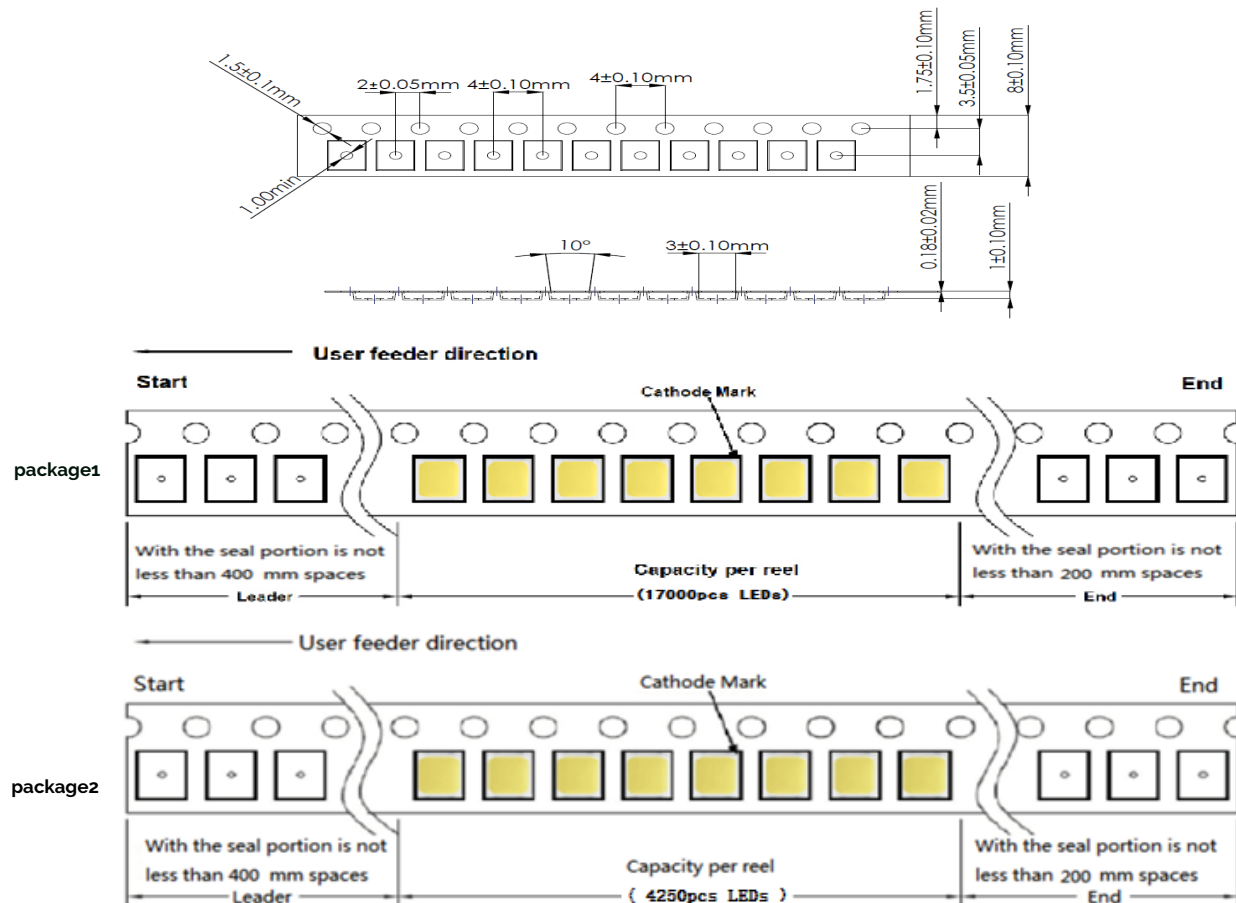
Figure 13: Emitter Reel Drawings



Note for Figure 13:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

Figure 14: Emitter Tape Drawings

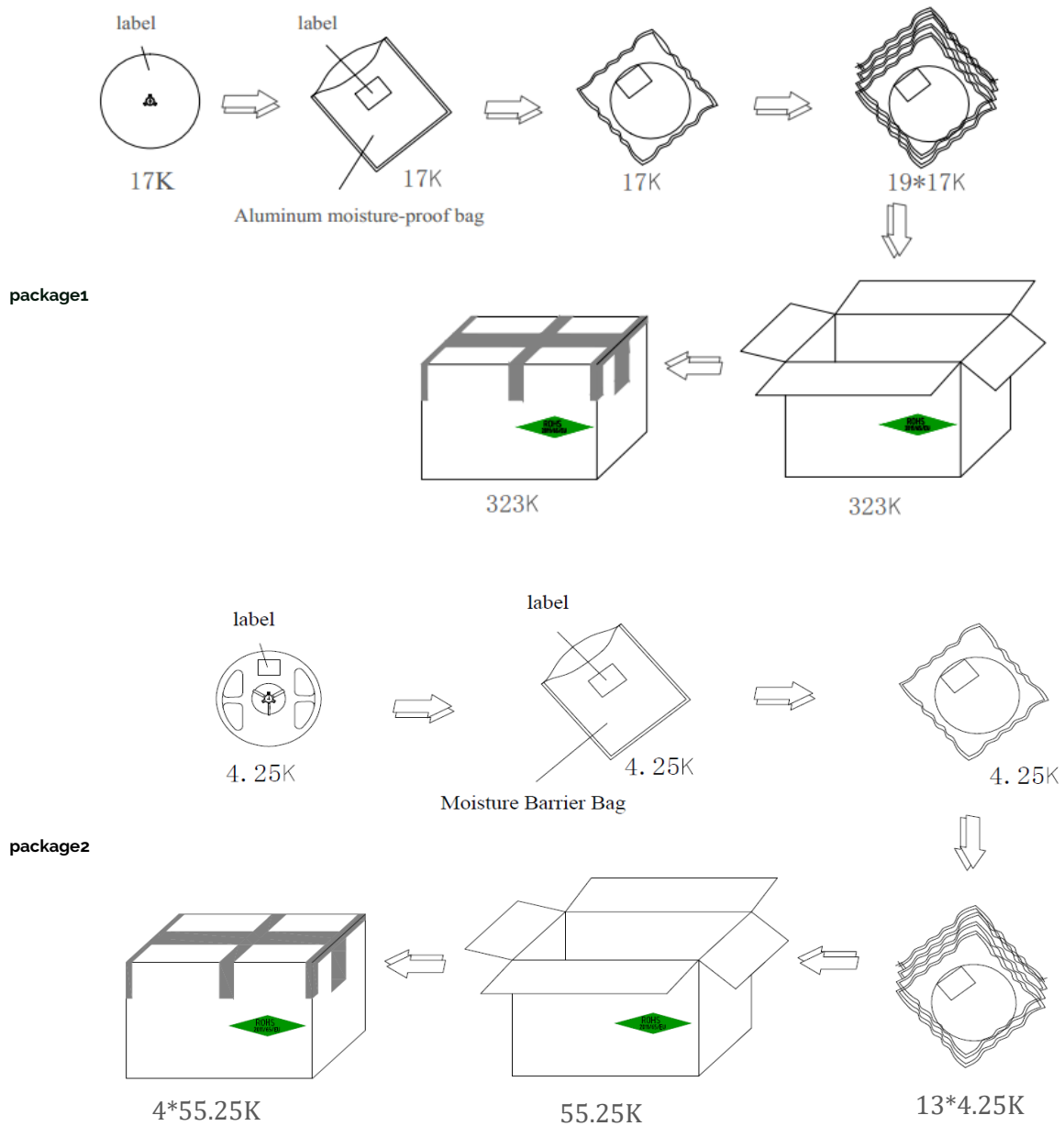


Note for Figure 14:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

Packaging

Figure 15: Emitter Reel Packaging Drawings



Note for Figure 15:

1. Drawings are not to scale.

Design Resources

Please contact your Bridgelux sales representative for assistance.

Precautions

CAUTION: CHEMICAL EXPOSURE HAZARD

Exposure to some chemicals commonly used in luminaire manufacturing and assembly can cause damage to the LED emitter. Please consult Bridgelux Application Note AN51 for additional information.

CAUTION: EYE SAFETY

Eye safety classification for the use of Bridgelux SMD LED emitter is in accordance with IEC specification EN62471: Photobiological Safety of Lamps and Lamp Systems. This product can be classified as Risk Group 1 or lower when operated at or below the maximum drive current. Please use appropriate precautions. It is important that employees working with LEDs are trained to use them safely.

CAUTION: RISK OF BURN

Do not touch the SMD LED emitter during operation. Allow the emitter to cool for a sufficient period of time before handling. The SMD LED emitter may reach elevated temperatures such that could burn skin when touched.

CAUTION

CONTACT WITH LIGHT EMITTING SURFACE (LES)

Avoid any contact with the LES. Do not touch the LES of the emitter or apply stress to the LES (yellow phosphor resin area). Contact may cause damage to the emitter

Optics and reflectors must not be mounted in contact with the LES (yellow phosphor resin area).

Disclaimers

MINOR PRODUCT CHANGE POLICY

The rigorous qualification testing on products offered by Bridgelux provides performance assurance. Slight cosmetic changes that do not affect form, fit, or function may occur as Bridgelux continues product optimization.

STANDARD TEST CONDITIONS

Unless otherwise stated, LED emitter testing is performed at the nominal drive current.

About Bridgelux: Bridging Light and Life™

At Bridgelux, we help companies, industries and people experience the power and possibility of light. Since 2002, we've designed LED solutions that are high performing, energy efficient, cost effective and easy to integrate. Our focus is on light's impact on human behavior, delivering products that create better environments, experiences and returns—both experiential and financial. And our patented technology drives new platforms for commercial and industrial luminaires.

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46410 Fremont Boulevard
Fremont, CA 94538 USA
Tel (925) 583-8400
Fax (925) 583-8401
www.bridgelux.com

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